



Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment

Marketing Name / Model

[List multiple models if applicable.]

HP A-MSR OAP FIC Module (JG277A)

HP MSR OAP VMware vSphere FIC Module (JG533A)

HP SBM FIC-OAP Module (JG589A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing		0

radioactive substances		
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2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#
Continuous vacuum desoldering system	
Desoldering tip	
Damp sponge	
Flux-cored solder	
tweezers	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove shielding finger 2 from filler panel 1.
2. Remove film 3 from filler panel 1.
3. Unscrew the screws on radiator 4, and then remove radiator 4.
4. Unscrew the screws on PCB 6, and then remove PCB 6.
5. Unscrew the screws on part 5, and then remove part 5.
6. Unscrew the screws on PCB 7, and then remove PCB 7.
7. Remove conformal coating (if any) and clean work area of any contamination, oxides, adhesives, residues or fluxes.
8. Install thermal drive desoldering tip handpiece.
9. Start with tip temperature of approximately 315°C and change as necessary.
10. Thermal shock tip with damp sponge.
11. Tin tip with solder. (See Figure 2.)
12. Confirm complete solder melt of contacted lead. (See Figure 3.)
13. For a flat lead, move lead back and forth; for a round lead, use a circular motion and apply vacuum while continuing lead movement. (See Figures 4&5.)
14. Lift tip from lead, hold vacuum for an additional 3 seconds to clear all molten solder from heater chamber. (See Figure 6.)
15. Repeat for all solder connections.
16. Re-tin tip end with solder and return handpiece to its stand.
17. Lift the component body free of the printed board.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

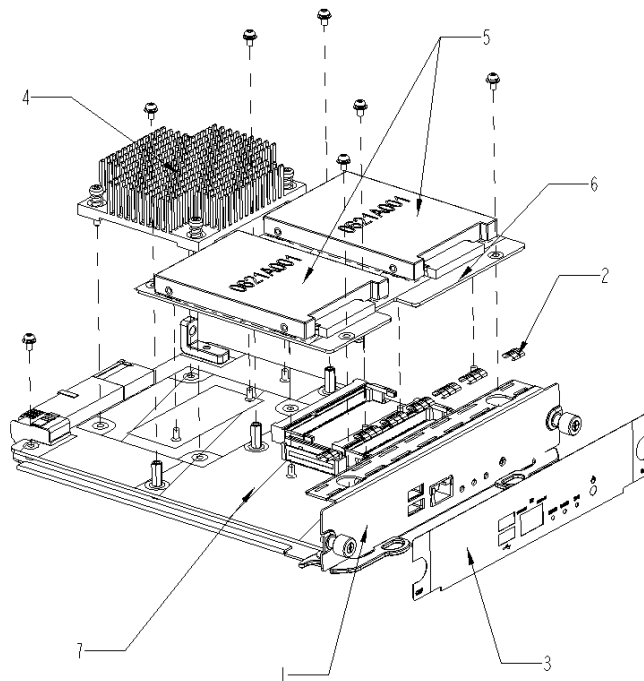


Figure 1 Treatments to filler panel

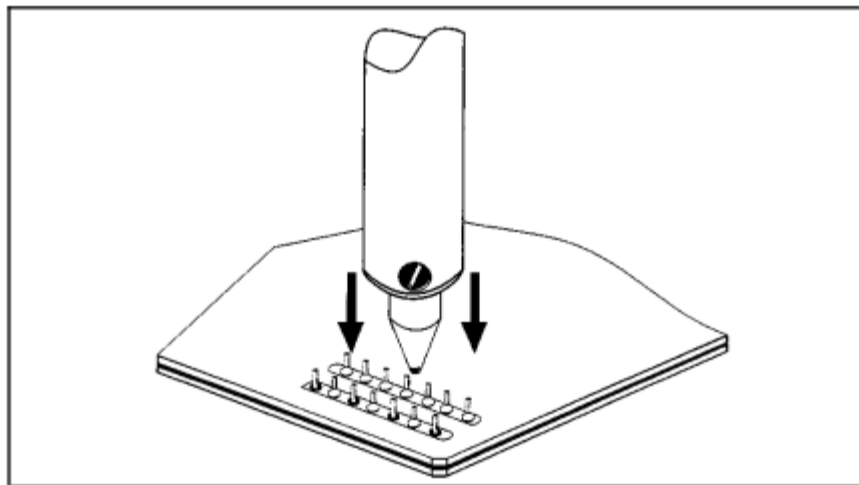


Figure 2 Position Tip

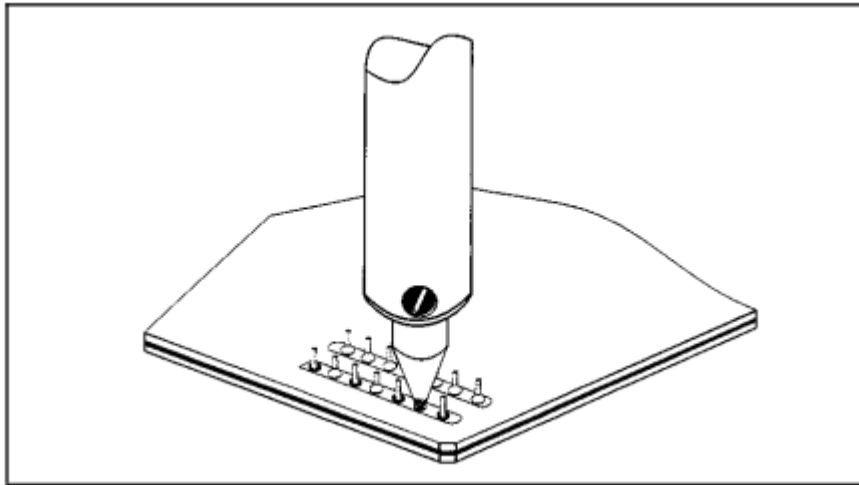


Figure 3 Melt Solder

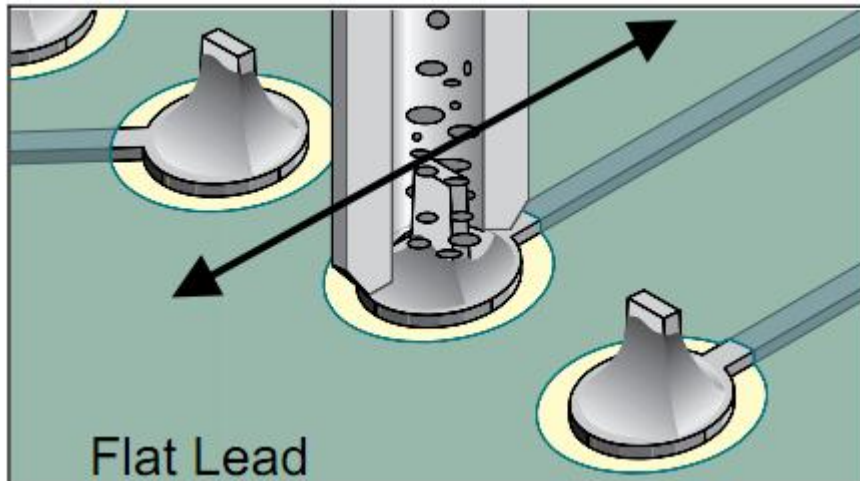


Figure 4 Move Lead & Apply Vacuum

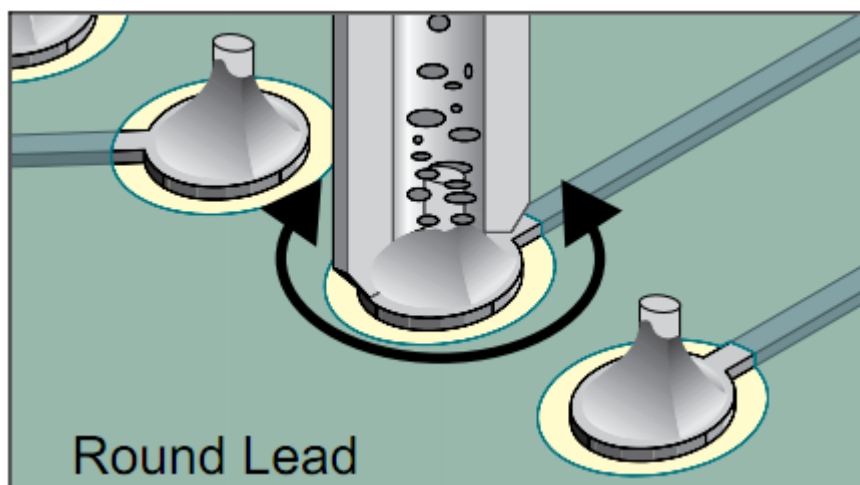


Figure 5 Move Lead & Apply Vacuum

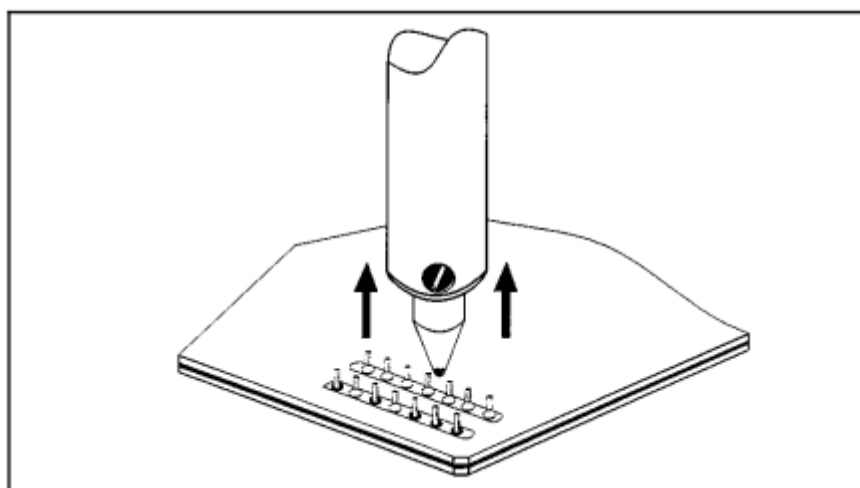


Figure 6 Lift Handpiece

4. Revised record

Date	Version	Author	Modify content
2012.11.09	V1	Wu Xuejun	Add the module JG587A and JG589A